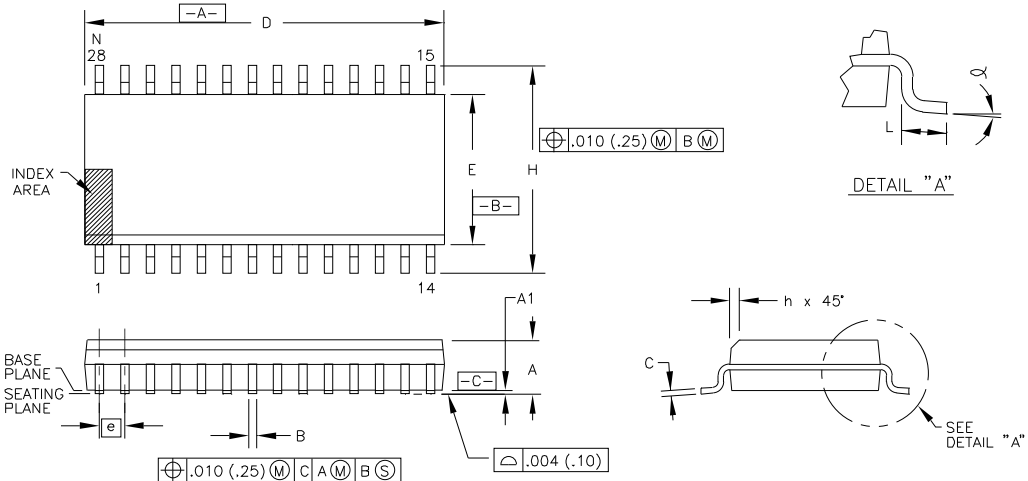


Package Number 217 - 28-Lead SOIC



DIM	INCHES		MILLIMETERS		N O T E	DIM	INCHES		MILLIMETERS		N O T E
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	.0926	.1043	2.35	2.65							
A1	.004	.0118	0.10	0.30							
B	.013	.020	0.33	0.51	7						
C	.0091	.0125	0.23	0.32							
D	.6969	.7125	17.70	18.10	2						
E	.2914	.2992	7.40	7.60	3						
e	.050	BASIC	1.27	BASIC							
H	.398	.419	10.11	10.65							
h	.010	.0295	0.25	0.75	4						
L	.020	.040	.508	1.02	5						
N	28		28		6						
α	0°	8°	0°	8°							

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .006 IN. (0.15 mm) PER SIDE.
- DIMENSION E DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED .010 IN. (0.25 mm) PER SIDE.
- THE CHAMFER ON THE BODY IS OPTIONAL. IF IT IS NOT PRESENT, A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE

CROSSHATCHED AREA.

- L IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTRATE.
- N IS THE NUMBER OF TERMINAL POSITIONS.
- THE LEAD WIDTH B, AS MEASURED .014 IN. (0.36 mm) OR GREATER ABOVE THE SEATING PLANE, SHALL NOT EXCEED A MAXIMUM VALUE OF .024 IN. (0.61 mm).
- LEAD TO LEAD COPLANARITY SHALL BE LESS THAN .004 IN. (0.10 mm) FROM SEATING PLANE.

PACKAGE NUMBER: ZZZ217 REV.: G
 JEDEC NUMBER: MS-013-AE
 WITH THE EXCEPTION OF DIM. H, L.



PACKAGE DRAWING

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